

TOSHIBA LED LAMP GaP GREEN LIGHT EMISSION

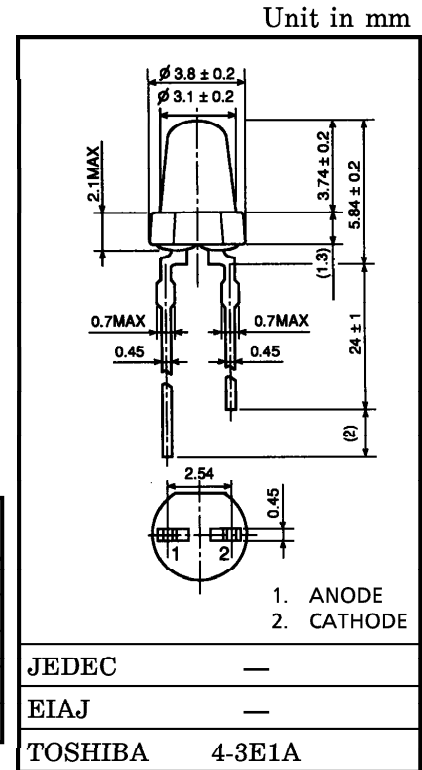
TLGD160

PANEL CIRCUIT INDICATOR

- All Plastic Mold Type
Clear Transparent Lens
- Low Drive Current, High Intensity Green Light Emission.
Recommended Forward Current : $I_F = 15 \sim 20\text{mA}$ (DC)
- All Plastic Molded Lens, Provides an Excellent ON-OFF Contrast Ratio.
- Fast Response Time, Capable of Pulse Operation.

MAXIMUM RATINGS ($T_a = 25^\circ\text{C}$)

CHARACTERISTIC	SYMBOL	RATING	UNIT
Forward Current (DC)	I_F	40	mA
Reverse Voltage	V_R	4	V
Power Dissipation	P_D	120	mW
Operating Temperature Range	T_{opr}	$-20 \sim 85$	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	$-30 \sim 100$	$^\circ\text{C}$



Weight : 0.12g

ELECTRO-OPTICAL CHARACTERISTICS ($T_a = 25^\circ\text{C}$)

CHARACTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Forward Voltage	V_F	$I_F = 20\text{mA}$	—	2.15	2.8	V
Reverse Current	I_R	$V_R = 4\text{V}$	—	—	5	μA
Luminous Intensity	I_V	$I_F = 20\text{mA}$ (Note)	140	300	—	mcd
			153	—	736	
Peak Emission Wave Length	λ_p	$I_F = 20\text{mA}$	—	567	—	nm
Spectral Line Half Width	$\Delta\lambda$	$I_F = 20\text{mA}$	—	25	—	nm

(Note) Rank selection carried out under next standard range respectively, although it needs $\pm 15\%$ sdditionary for guaranteed limits.

P : 180-360mcd Q : 320-640mcd

Each rank products is classified by package unit, and (PQ) includes P and Q.

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PRECAUTION

Please be careful of the followings.

- Soldering temperature : 260°C MAX. Soldering time : 3s MAX.
(Soldering portion of lead : up to 2mm from the body of the device)
- If the lead is formed, the lead should be formed up to 5mm from the body of the device without forming stress to the resin. Soldering should be performed after lead forming.

